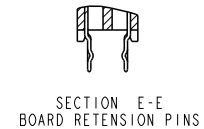
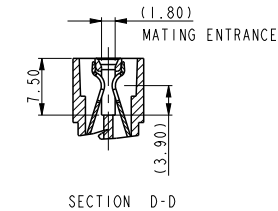
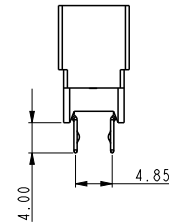
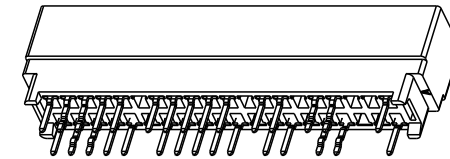
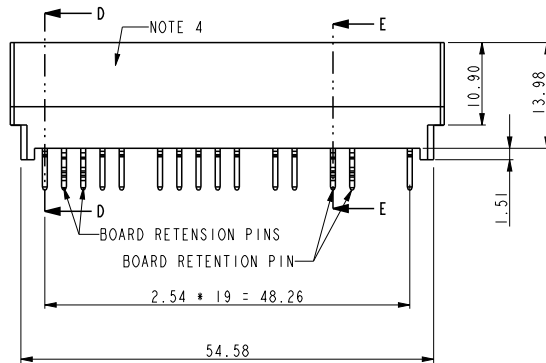
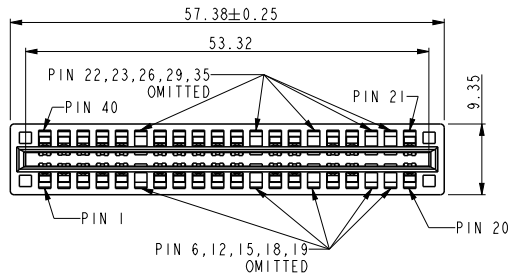


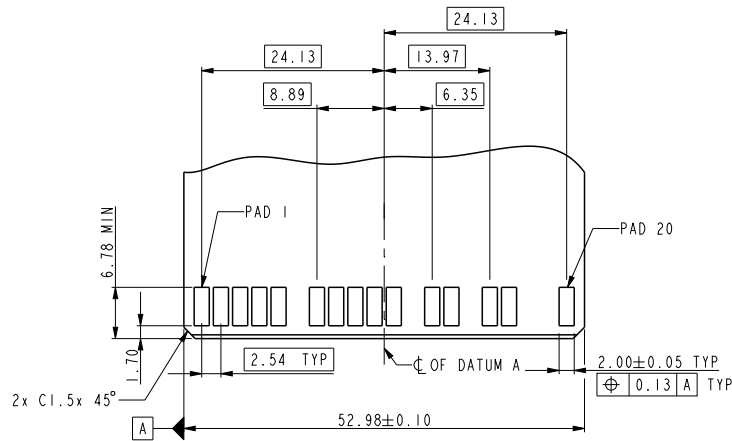
PRODUCT NO  
10046971-044LF



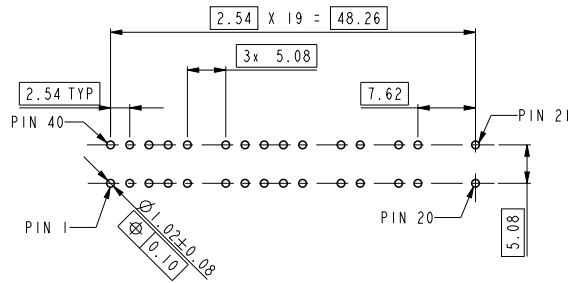
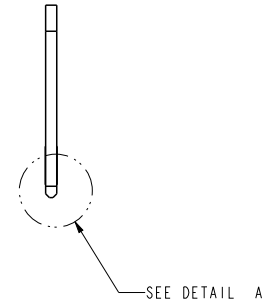
- NOTE:
- MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC,  
UL 94 V-0 FLAME RETARDANT.  
TERMINAL: HIGH CONDUCTIVITY COPPER ALLOY.  
PLATING SPEC AS BELOW:  
Ni 50u" UNDER PLATED.  
Au 30u" OVER CONTACT AREA (ONE SIDE)  
MATTE PURE TIN 120u" OVER SOLDERING AREA.
  - PACKING SPEC. GS-14-937
  - PRODUCT SPEC. GS-12-338.
  - MANUFACTURER'S NAME, P/N AND DATE CODE TO APPEAR ON THIS SURFACE AS PER GS-24-007.

- PART NUMBER 10046971-044LF MEETS EUROPEAN UNION DIRECTIVE AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A CIRCUIT BOARD.
- THE PINS 6, 12, 15, 18, 19, 22, 23, 26, 29, 35 ARE OMITTED.

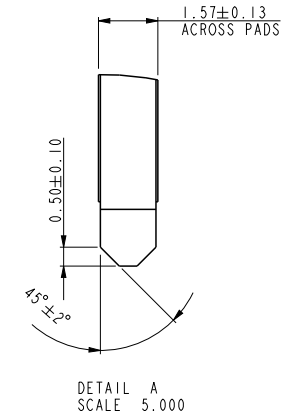
spec ref	*	dr	Julia Wang	2013/12/18	projection	MM	size	A4	scale	1.000
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Julia Wang	2014/03/20		←→	ecn no	-	rel level	Released
ISO 406 ISO 1101		chr	-	-						
surface	linear	appr	Pei-Ming Zheng	2014/03/20	product family	Power Edge Card	rev		10046971-044	A
ISO 1302	angular	www.fci.com		cat. no.	*	Product - Customer Drw	sheet 1 of 2			
	0.X ±0.50	FCI		title	VERTICAL TYPE		dwg no	10046971-044		
	0.XX ±0.25				2X20P(10P OMITTED)					
	0.XXX ±0.13									
	0° ±2°									



RECOMMENDED MATING BOARD



RECOMMENDED PC BOARD LAYOUT AND THE THICKNESS IS 3.18mm



dr	Julia Wang	2013/12/18	projection 	MM ←→	size	A4	scale	1.000
eng	Julia Wang	2014/03/20			ecn no	-		
chr	-	-			rel level	Released		
appr	Pei-Ming Zheng	2014/03/20	product family	Power Edge Card	rev	A		
		title	VERTICAL TYPE 2X20P(10P OMITTED)		dwg no	10046971-044	sheet 2 of 2	
www.fci.com		cat. no.	*	Product - Customer Drw	sheet 2 of 2			



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